



Materials and Finish

Housing Material:
 high temp. thermoplastic,
 (reflow process compatible)
 UL 94V-0 rated, black color

Oxygen Index: 36%

Poly Mass: 2.4 g

Recommended Reflow Temperature:
 230°C for 30 seconds,
 260°C max.

Design meets UL 1863 Sec. 8
 Electrical Probe and Sec. 20
 Child Finger test requirements

Shield Material:
 copper alloy, 0.20mm thick,
 nickel plated 90u" min,

Contact Material: phosphor bronze

Contact Plating Options:
 Standard: 0.0001" Nickel
 Plating, Selective Plating
 Gold Flash on Contact
 Area, Tin/Lead on Termination End

50: 0.0001" Nickel Plating,
 Selective Plating 0.000050"
 Gold on Contact Area to
 Comply with FCC Requirements
 Under No. 47 C.F.R. Part 68,
 Subpart F, Tin/Lead on
 Termination End

Electrical Characteristics

Insulation Resistance:
 500 Megohms min.

Dielectric Withstanding Voltage:
 1000V rms, 60Hz

Contact Resistance:
 20 milliohms max.

Current Rating: 1.5 Amps

Durability Rating:
 1000 mating cycles min.

Operating Temperature:
 -40°C to +85°C

Electrical Performance

Category 5 100MHz Bandwidth Performance
 Attenuation @ 100MHz less than 0.13dB
 Performance meets near end crosstalk (NEXT)
 Requirements of -40dB @ 100MHz per
 EIA/TIA 568A in applications where UL
 Approved Category 5 cable (GA27-3773-1)
 is used
 Shielded types offer 20dB shielding from
 30MHz to 300MHz

Tolerances	
X.X ± 0.25	
X.XX ± 0.15	
Unless Stated	
Otherwise	

Part Number	t_gold	Packaging
GM-SMT2-S2-88	Flash	Bulk
GM-SMT2-S2-88-50	50u"	Bulk
GM-SMT2-S2-88-TR	Flash	Tape & Reel
GM-SMT2-S2-88-50TR	50u"	Tape & Reel

REVISION	DATE	DESCRIPTION	DRAWN BY	CHECKED BY	UNITS
A6	4/17/02	Ref ECD 02-044	C. Leiva		mm
A7	6/4/02	Ref ECD 02-038	REVISED BY	APPROVED BY	DATE
B1	7/15/02	Ref ECD 02-072	C. Leiva	K. Wallace	7/27/97

GM-SMT2-S2-88

Right Angle Modular Jack, Shielded
 8 position, 8 contacts, Surface Mount

